

SURFACE MOUNT DUAL, IN SERIES SILICON SWITCHING DIODES





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMPD7000 type is a ultra-high speed silicon switching diode manufactured by the epitaxial planar process, in an epoxy molded surface mount package, connected in a series configuration, designed for high speed switching applications.

MARKING CODE: C5C

MAXIMUM RATINGS: (TA=25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Average Forward Current	IO	200	mA
Peak Forward Current	IFM	500	mA
Power Dissipation	PD	350	mW
Operating and Storage Junction Temperature	т _Ј , т _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (TA=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
IR	V _R =50V			300	nA
IR	V _R =50V, T _A =125°C			100	μA
IR	V _R =100V			500	nA
BVR	I _R =100μA	100			V
VF	I _F =1.0mA	0.55		0.70	V
VF	I _F =10mA	0.67		0.82	V
VF	I _F =100mA	0.75		1.10	V
CT	V _R =0, f=1.0MHz		1.5	2.6	pF
t _{rr}	$I_R=I_F=10mA$, $R_L=100\Omega$, Rec. to 1.0mA		2.0	4.0	ns

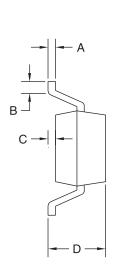
R7 (27-January 2010)

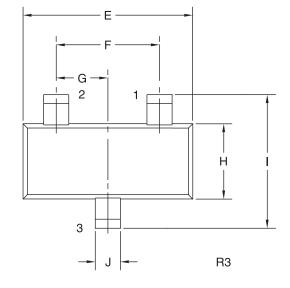


CMPD7000

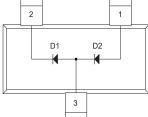
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SOT-23 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



LEAD CODE:

- 1) Anode D2 2) Cathode D1
- 3) Anode D1, Cathode D2

MARKING CODE: C5C

DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
А	0.003	0.007	0.08	0.18			
В	0.006	-	0.15	-			
С	-	0.005	-	0.13			
D	0.035	0.043	0.89	1.09			
E	0.110	0.120	2.80	3.05			
F	0.075		1.90				
G	0.037		0.95				
Н	0.047	0.055	1.19	1.40			
	0.083	0.098	2.10	2.49			
J	0.014	0.020	0.35	0.50			
COT 22 (DEV/- D2)							

SOT-23 (REV: R3)

R7 (27-January 2010)

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OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

ss your design challenges.

· Custom product packing

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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